

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claims 1-10(canceled).

11. (original): A method for manufacturing an electronic component, comprising the steps of:

preparing a pair of conductive wires;

bending one end portion of the conductive wires outwards at an angle of about 90 degrees;

forming a flat portion by press extending at least the portion on the tip side from the bending point so as to be extended substantially parallel to a lead portion of the lead terminal;

forming a cup-shaped holder portion by bending the flat portion inwards;

holding both end portions of a piezoelectric element in a pair of the cup-shaped holder portions; and

electrically and mechanically connecting the cup-shaped holder portions and the electrodes formed in both end portions of the piezoelectric element by using a conductive joining material.

12. (original): A method for manufacturing an electronic component as

claimed in claim 11, further comprising the step of plating molten solder on the conductive wire.

13. (original): A method for manufacturing an electronic component as claimed in claim 11, wherein the lead portions at the other end of the conductive wires are welded and fixed to a metal hoop material with pilot holds having a fixed distance therebetween.

14. (original): A method for manufacturing an electronic component as claimed in claim 11, wherein the step of bending one end portion of the conductive wires outwards at an angle of about 90 degrees is done at a location about two thirds away from the tip of the flat portions.

15. (original): A method for manufacturing an electronic component as claimed in claim 11, further comprising the step of providing a capacitor element between the cup-shaped holder portions and a tip portion of one of the lead terminals, and electrically and mechanically connecting the capacitor to the holder portions via the conductive joining material.

16. (original): A method for manufacturing an electronic component as claimed in claim 11, further comprising the step of integrally sealing the piezoelectric element, the pair of lead terminals and the conductive joining material in a packaging resin.

17. (original): A method for manufacturing an electronic component according to Claim 11, wherein the electronic component is a resonator.

18. (original): A method for manufacturing an electronic component according to Claim 11, wherein the piezoelectric element is an energy trap thickness shear vibration mode element.

19. (original): A method for manufacturing an electronic component according to Claim 11, wherein each of the lead terminals are made of a round lead wire of about 0.48 mm in diameter.

20. (original): A method for manufacturing an electronic component according to Claim 11, wherein each of the lead terminals includes a wire made of a low-carbon steel and having copper plated on a surface thereof and a molten solder plated on the copper plating.

21. (original): A method for manufacturing an electronic component according to Claim 11, wherein a width of the flat portions is about 0.8 mm to about 1.0 mm and a thickness of the flat portions is about 0.15 mm to about 0.2 mm.